



Material Content Data Sheet



Sales Product Name				BTS50080-1TMB		Issued		25. September 2017	
MA#				MA001044088					
Package				PG-TO220-7-12		Weight*		2118.96 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.391	0.30	0.30	3016	3016	
leadframe	non noble metal	iron	7439-89-6	0.908	0.04		429		
	inorganic material	phosphorus	7723-14-0	0.272	0.01		129		
	non noble metal	copper	7440-50-8	906.793	42.79	42.84	427940	428499	
wire	non noble metal	aluminium	7429-90-5	2.539	0.12	0.12	1198	1198	
encapsulation	organic material	carbon black	1333-86-4	8.868	0.42		4185		
	plastics	epoxy resin	-	97.547	4.60		46035		
	inorganic material	silicondioxide	60676-86-0	484.777	22.88	27.90	228780	279000	
leadfinish	non noble metal	tin	7440-31-5	23.005	1.09	1.09	10857	10857	
plating	non noble metal	nickel	7440-02-0	0.216	0.01		102		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	102	
glue	plastics	Polyimide	26023-21-2	0.143	0.01	0.01	67	67	
solder	noble metal	silver	7440-22-4	0.098	0.00		46		
	non noble metal	tin	7440-31-5	0.078	0.00		37		
	non noble metal	lead	7439-92-1	3.746	0.18	0.18	1768	1851	
heatspreader	inorganic material	phosphorus	7723-14-0	0.175	0.01		83		
	non noble metal	iron	7439-89-6	0.584	0.03		275		
	non noble metal	copper	7440-50-8	582.824	27.51	27.55	275052	275410	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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